

## EAST Search History

| Ref # | Hits  | Search Query   | DBs  | Default Operator | Plurals | Time Stamp       |
|-------|-------|--|--|------------------|---------|------------------|
| S1    | 37735 | ("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool)  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/08/01 10:12 |
| S2    | 6389  | ("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool)  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/08/01 10:14 |
| S3    | 686   | ("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool) and polishing  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/08/01 10:42 |
| S4    | 2     | "6809029".pn.  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/08/01 10:15 |
| S5    | 3     | ("6486055"   "6602787").PN. OR ("6809029").URPN.   | US-PGPUB; USPAT; USOCR                             | OR               | ON      | 2006/08/01 10:20 |
| S6    | 101   | ("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool) and polishing and cup  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/08/01 12:05 |
| S7    | 587   | ("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool) and \$5polishing not S6  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/08/01 11:14 |
| S8    | 62    | ("204"/198-241.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool) and \$5polishing and (fac\$3 near5 (up upward)) with (substrate wafer) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2006/08/01 12:05 |

## EAST Search History

|     |     |   |  |    |    |                  |
|-----|-----|---|--|----|----|------------------|
| S9  | 10  | ("20020029961"   "5853559"   "6126798"   "6132587"   "6176992"   "6179982"   "6179983"   "6375823"   "6402925"   "6416647").PN.   | US-PGPUB; USPAT; USOCR                             | OR | ON | 2006/08/01 11:28 |
| S10 | 2   | ("5084149"   "5256274").PN.   | US-PGPUB; USPAT; USOCR                             | OR | ON | 2006/08/01 12:02 |
| S11 | 95  | ("204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool) and \$5polishing and (fac\$3 near5 (up upward)) with (substrate wafer)                               | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/01 15:49 |
| S12 | 2   | "6077412".pn.   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/01 15:01 |
| S13 | 56  | ("4391694"   "5000827"   "5024746"   "5256274"   "5368711"   "5429733"   "5437777"   "5441629"   "5447615"   "5516414"   "5597460"   "5830805"   "5853559"   "5865984"   "5932076").PN. OR ("6077412").URPN.  | US-PGPUB; USPAT; USOCR                             | OR | ON | 2006/08/01 15:40 |
| S14 | 5   | S13 and electroless and annealing   | US-PGPUB; USPAT; USOCR                             | OR | ON | 2006/08/01 15:49 |
| S15 | 26  | ("204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool) and \$5polishing and (fac\$3 near5 (up upward)) with (substrate wafer) and electroless and annealing | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/01 15:58 |
| S16 | 108 | ("204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 plating electrodeposit\$5 electroplat\$5) and (apparatus system chamber tool) and \$5polishing and (substrate wafer) and electroless and annealing                                 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/01 15:50 |

## EAST Search History

|     |    |  |                              |    |    |                  |
|-----|----|--|------------------------------|----|----|------------------|
| S17 | 46 | ("5363171"   "5393624"  <br>"5658183"   "5719495"   "5872633"<br>  "5924058"   "5964643"  <br>"6004047"   "6017437"   "6025600"<br>  "6045618"   "6051284"  <br>"6077412"   "6110011"   "6122046"<br>  "6159073"   "6168693"  <br>"6187072"   "6190234"   "6193802"<br>  "6194628"   "6197181"  <br>"6201240"   "6208751"   "6231743"<br>  "6238539"   "6244931"  <br>"6247998"   "6255222"   "6270634"<br>  "6277194"   "6280289"  <br>"6283692"   "6284622"   "6296548"<br>  "6303395"   "6303931"  <br>"6309276"   "6318384"   "6331490"<br>  "6352467"   "6444481"  <br>"6454899"   "6511898"  <br>"6534328").PN. OR ("6747734").<br>URPN. | US-PGPUB;<br>USPAT;<br>USOCR | OR | ON | 2006/08/01 16:15 |
| S18 | 1  | S12 and electroless  | US-PGPUB;<br>USPAT;<br>USOCR | OR | ON | 2006/08/01 16:16 |